

L.E.W. TECHNIQUES LTD

**NOW
AVAILABLE**

Pre-deposited AuSn for Thin Film microcircuits

L.E.W. Techniques has expanded its capabilities in Thin Film microcircuits with the addition of pre-deposited AuSn solder. The vacuum-deposited solder can be selectively applied to areas where critical devices will be mounted. The solder is applied over existing conductors and is typically 3-5 microns thick. Standard alloy ratio is 72Au/28Sn. Parts can be tailored to match individual requirements.

Typical benefits:

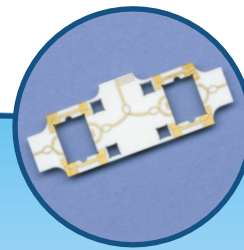
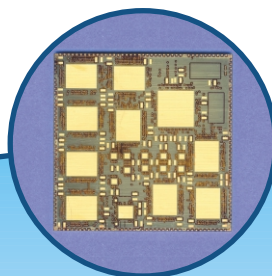
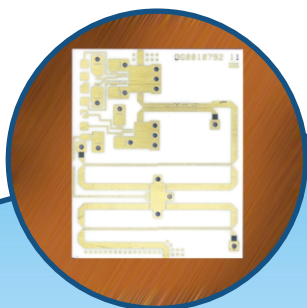
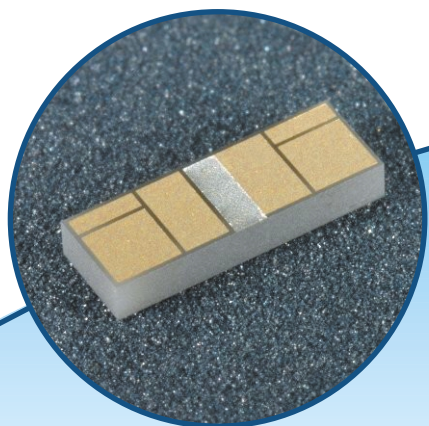
- Excellent reflow properties
- Thin, uniform layers
- Void-free joints
- Flux-free assembly

Typical applications:

- Laser diode heatsinks
- High power hybrids
- Photodiode mounts
- Optical sub-assemblies

The addition of pre-deposited AuSn strengthens our existing capabilities in Thin Film on ceramic, which include:

- Fine line microcircuits on AlN, Al₂O₃, quartz, glass, ferrite, etc
- Filled vias and plated thru-holes
- Integrated resistors trimmed to tight tolerance
- Laser profiling and micro dicing



For further information or to discuss
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